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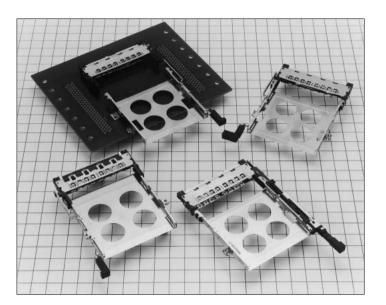
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Single Slot SMT Connectors For Card-Bus Based PC Cards

IC11S Series



PC Card Standard Compliant



■Features

1. PC Card Standard compliant:

- · Grounding is required to meet the high speed signal requrements of the PC card standard. Grounding reliability is achieved with a grounding plate and 8 grounding contacts.
- Type I, type II and type III cards are covered.
- · Terminals for ground clipping are provided.

2. Space saving

Smaller size reduces occupied area on PC boards as compared to previous products.

3. Reduced Height:

Connector height is minimized to 5.6mm, making possible thinner product designs.

4. Eject mechanism with high-level functionality

Hirose Electric's original ejection mechanism provides an higher degree of card ejection over existing products. This improves the operational qualities of card removal. (Patents pending)

5. Wide Variety of Options Available

- · Standard type mounts to the top of the PC board and reverse type mounts on the underside of the board
- · Three types of eject buttons; rigid, flexible and POP-UP.All types can be installed on the right or left side of the ejector.
- · Available with standoff to utilize space under the connector for mounting other parts.

6. Light-weight

Weight of 12.7g for normal button type helps achieve the reduced weight required in today's products.

Wide variety of options

- (1)Board Mounting
 - ①Standard type
 - 2 Reverse type
- (2)Types of eject button
 - ①Rigid button
 - ②Foldering button
 - ③Pop-up button
- (3)Position of eject buttons
 - 1)Right
 - ²Left
- (4)Standoffs
 - ①None
 - 22.2mm



■Product Specifications

	Current rating	0.5A	Operating temperature	-55°C to +85°C(Note.1)	Storage temperature	-40°C to +70°C(Note.2)
Ratings	Voltage rating	125V AC	Operating humidity	Relativehumidity 95% max. (With no dew-fall)	Storage humidity	40% to 70%(Note.2)

Item	Specification	Conditions			
1.Insulation resistance	1000M ohms min.	500V DC			
2.Withstanding voltage	No flashover or insulation breakdown.	500V AC			
3.Contact resistance	60m ohms max. (initial value)	1mA			
4.Vibration	No electrical discontinuity of 100ns or more	Frequency: 10 to 2000 Hz, full amplitude of 1.52 mm or acceleration of 147 m/s²(peak), 4 hours in each of the 3 directions.			
5.Humidity (Steady state)	Insulation resistance: 100M ohms min.	96 hours at temperature of 40°C and humidity of 90% to 95%			
6.Temperature cycle	Insulation resistance: 100M ohms min.	(-55°C:30min.→+5°C to 35°C:MAX 5min→85°C:30min→+5 -35°C:MAX 5min.) 5 cycles			
7.Durability (Insertion/withdrawal)	Variations from initial contact resistance: 20m ohms max.	10000 cycles at 400 to 600 cycles per hour			
8.Resistance to Soldering heat	No deformation of components affecting performance.	Reflow: At the recommended temperature profile Manual soldering: 300℃ for 3 seconds			

Note 1: Includes temperature rise caused by current flow.

Note 2: The term "storage" refers to products stored for long period of time prior to mounting and use. Operating Temperature Range and Humidity range covers non-conducting condition of installed connectors in storage, shipment or during transportation.

■Material

SMT unit

	Parts	Material	Finish	Remarks
Insulator		PPS	Black	UL94V-0
	Card connected section	Brass	Contact section: gold plating	
Contact	Card connected section	brass	Lead section: solder plating	
Contact	Ground plate	Phosphor bronze	Contact section: gold plating	
	Ground plate	Phosphor bronze	Lead section: solder plating	
Eject metal	fittings	Stainless steel		

Guide unit

	Item		Material	Finish	Remarks
	Guide plate		Stainless steel		
	Push rod		Stainless steel		
	Rigid button type	resin section	PBT	Color : Black	UL94V-0
		resin section	PBT	Color : Black	UL94V-0
	Foldering button type	spring	Stainless steel		
	button type	spring pin	Stainless steel		
Eject Button		resin section	PBT	Color : Black	UL94V-0
	DOD LID turns	frame metal	Stainless steel		
	POP-UP type	spring	Steel		
		pin	Brass	Nickel plating	
	Nut		Steel		M2X0.4

■Ordering Information

SMT Unit

IC11S A - 68 PLR - 1.27SF - EJ R

Series name : IC11S	6 1.27SF: 1.27mm pitch SMT connector			
Standoff type Blank: none				
A : 2.2mm	With ejector EJ: with ejector			
Number of contacts : 68				
Board Mounting Type: PL : standard type PLR : reverse type	Eject button positionsR : rightL : left			

Guide Unit

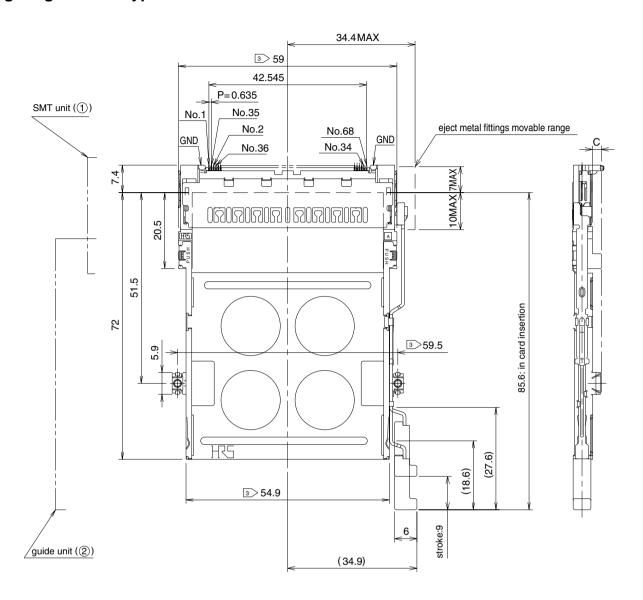
IC11S A - BUR - FEJ R

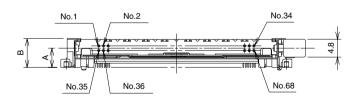
Series name : IC11S Standoff type Blank: none A: 2.2mm	Eject button type EJ : rigid button FEJ : Foldering button PEJ : POP-UP button
Board Mounting Type BD : standard type BUR : reverse type	Eject button positionsR : rightL : left

(Note.) IC11S Series will be used in combination of SMT unit with guide unit. When using, please select the same type for the following items. Please note that other combinations cannot be used.

> • Series name (⊕⇔8) Standoff (**2**⇔**9**) • Board-installed type (4⇔⊕) • Eject button positions **(⑦⇔②**)

Right rigid button type



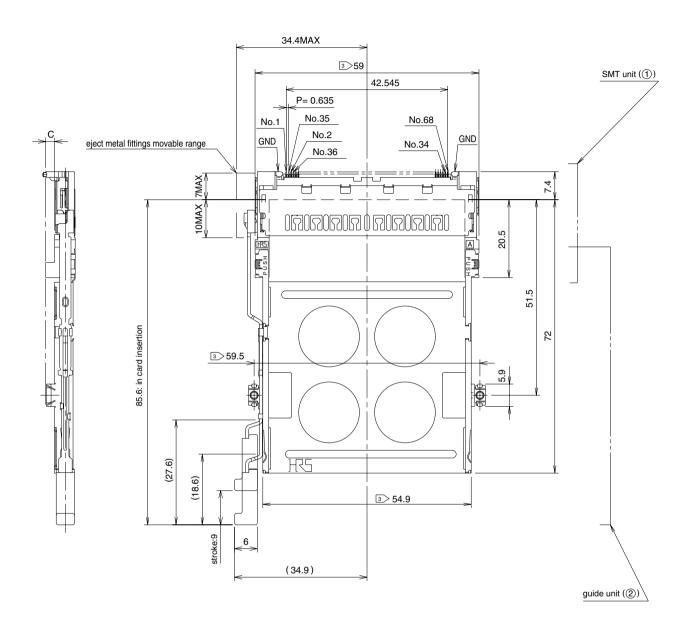


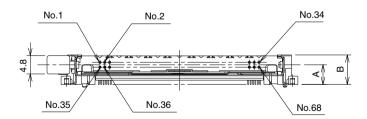
Standoff	①SMT un	it	②Guide ur	nit	Α	В	С	Weight
type	Part Number	CL No.	Part Number	CL No.	(mm)	(mm)	(mm)	(g)
none	IC11S-68PL-1.27SF-EJR	640-1007-3	IC11S-BD-EJR	640-1071-2	3	5.6	0.1	12.7
2.2mm	IC11SA-68PL-1.27SF-EJR	640-1009-9	IC11SA-BD-EJR	640-1073-8	5.2	7.8	2.3	13.1

Note.1) This figure illustrates grouping of SMT unit(1) and guide unit(2) together.

Note.2) Dimensions for card fitting are in accordance with "PC Card Standard".

Left rigid button type



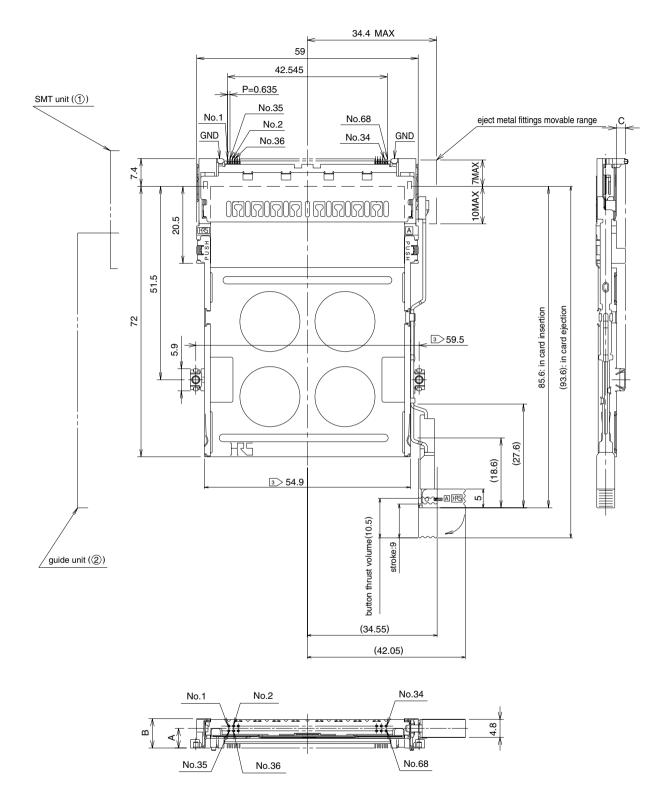


Standoff	①SMT un	it	②Guide u	nit	Α	В	С	Weight
type	Part Number	CL No.	Part Number	CL No.	(mm)	(mm)	(mm)	(g)
none	IC11S-68PL-1.27SF-EJL	640-1008-6	IC11S-BD-EJL	640-1072-5	3	5.6	0.1	12.7
2.2mm	IC11SA-68PL-1.27SF-EJL	640-1010-8	IC11SA-BD-EJL	640-1074-0	5.2	7.8	2.3	13.1

Note.1) This figure illustrates grouping of SMT unit(1) and guide unit(2) together.

Note.2) Dimensions for card fitting are in accordance with "PC Card Standard".

Right flexible button type

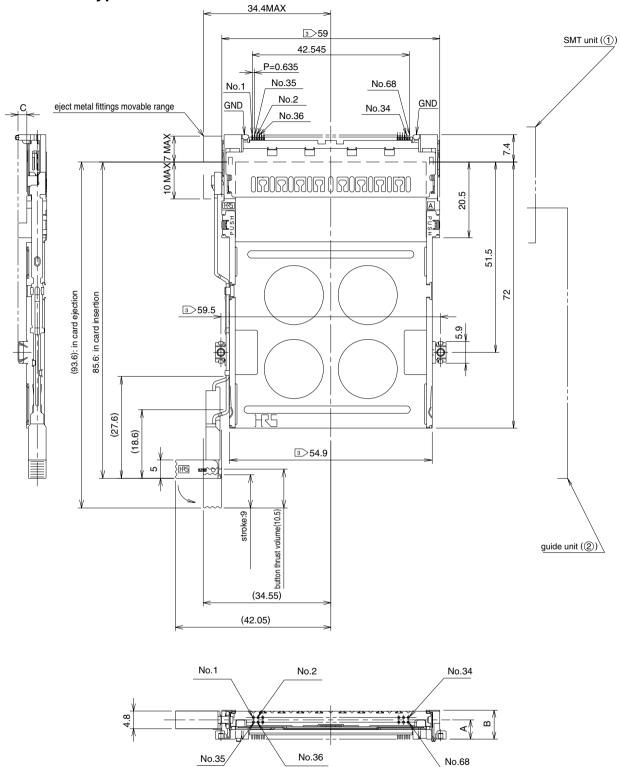


Stando	①SMT ur	nit	②Guide u	nit	А	В	С	Weight
type	Part Number	CL No.	Part Number	CL No.	(mm)	(mm)	(mm)	(g)
none	IC11S-68PL-1.27SF-EJR	640-1007-3	IC11S-BD-FEJR	640-1075-3	3	5.6	0.1	13.1
2.2mr	n IC11SA-68PL-1.27SF-EJR	640-1009-9	IC11SA-BD-FEJR	640-1077-9	5.2	7.8	2.3	13.5

Note.1) This figure illustrates grouping of SMT unit(1) and guide unit(2) together.

Note.2) Dimensions for card fitting are in accordance with "PC Card Standard".

Left flexible. button type

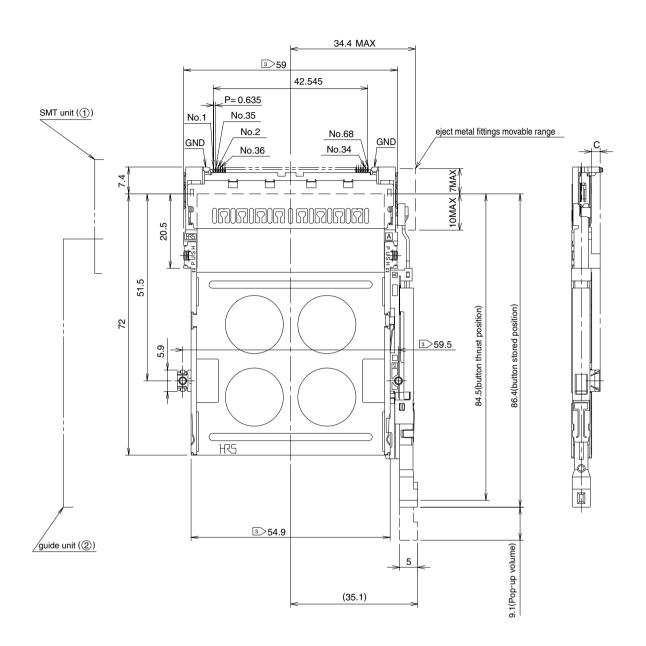


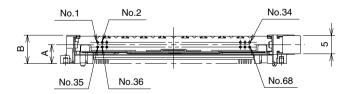
Standoff	①SMT ur	nit	②Guide u	nit	Α	В	С	Weight
type	Part Number	CL No.	Part Number	CL No.	(mm)	(mm)	(mm)	(g)
none	IC11S-68PL-1.27SF-EJL	640-1008-6	IC11S-BD-FEJL	640-1076-6	3	5.6	0.1	13.1
2.2mm	IC11SA-68PL-1.27SF-EJL	640-1010-8	IC11SA-BD-FEJL	640-1078-1	5.2	7.8	2.3	13.5

Note.1) This figure illustrates grouping of SMT unit(1) and guide unit(2) together.

Note.2) Dimensions for card fitting are in accordance with "PC Card Standard".

Right POP-UP button type



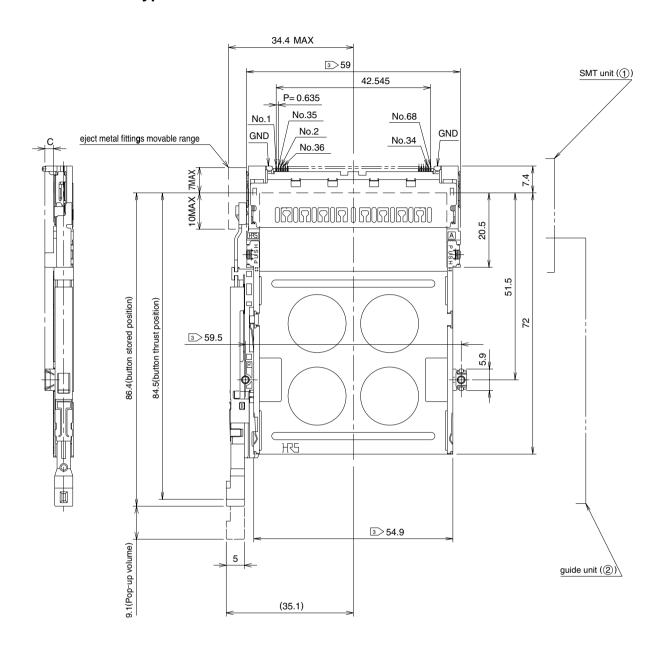


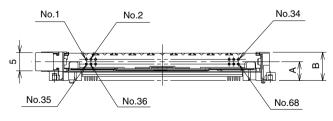
Standoff	①SMT un	it	②Guide u	nit	Α	В	С	Weight
type	Part Number	CL No.	Part Number	CL No.	(mm)	(mm)	(mm)	(g)
none	IC11S-68PL-1.27SF-EJR	640-1007-3	IC11S-BD-PEJR	640-1081-6	3	5.7	0.1	14.7
2.2mm	IC11SA-68PL-1.27SF-EJR	640-1009-9	IC11SA-BD-PEJR	640-1083-1	5.2	7.9	2.3	15.1

Note.1) This figure illustrates grouping of SMT unit(1) and guide unit(2) together.

Note.2) Dimensions for card fitting are in accordance with "PC Card Standard".

Left POP-UP button type



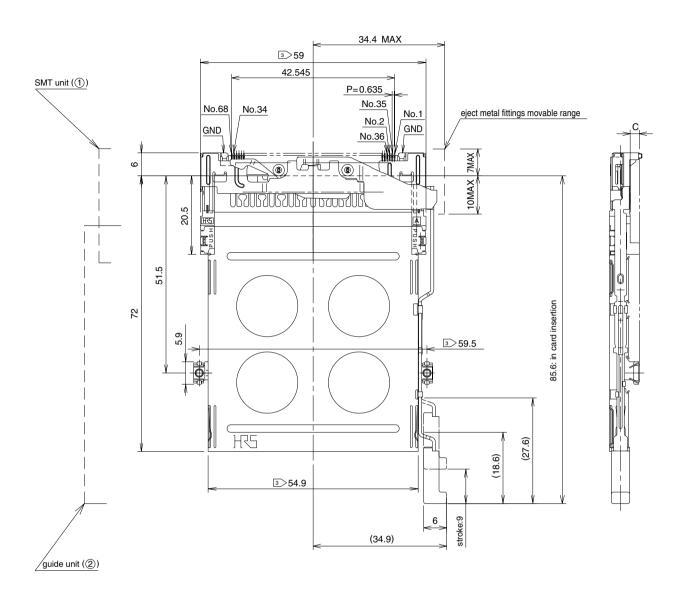


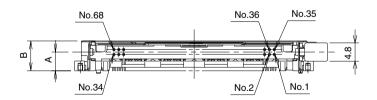
Standoff	①SMT un	it	②Guide u	nit	Α	Α	С	Weight
type	Part Number	CL No.	Part Number	CL No.	(mm)	(mm)	(mm)	(g)
none	IC11S-68PL-1.27SF-EJL	640-1008-6	IC11S-BD-PEJL	640-1082-9	3	5.7	0.1	14.7
2.2mm	IC11SA-68PL-1.27SF-EJL	640-1010-8	IC11SA-BD-PEJL	640-1084-4	5.2	7.9	2.3	15.1

Note.1) This figure illustrates grouping of SMT unit(1) and guide unit(2) together.

Note.2) Dimensions for card fitting are in accordance with "PC Card Standard".

Right rigid button type



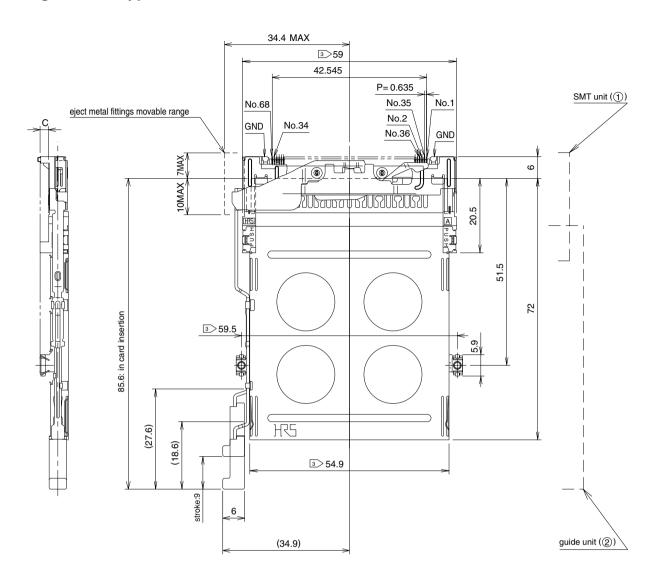


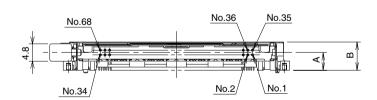
Standoff	①SMT un	①SMT unit ②Guide unit		Α	В	С	Weight	
type	Part Number	CL No.	Part Number	CL No.	(mm)	(mm)	(mm)	(g)
none	IC11S-68PLR-1.27SF-EJR	640-1003-2	IC11S-BUR-EJR	640-1055-6	2.7	5.6	0.1	13.1
2.2mm	IC11SA-68PLR-1.27SF-EJR	640-1005-8	IC11SA-BUR-EJR	640-1057-1	4.9	7.8	2.3	13.6

Note.1) This figure illustrates grouping of SMT unit(1) and guide unit(2) together.

Note.2) Dimensions for card fitting are in accordance with "PC Card Standard".

Left rigid button type



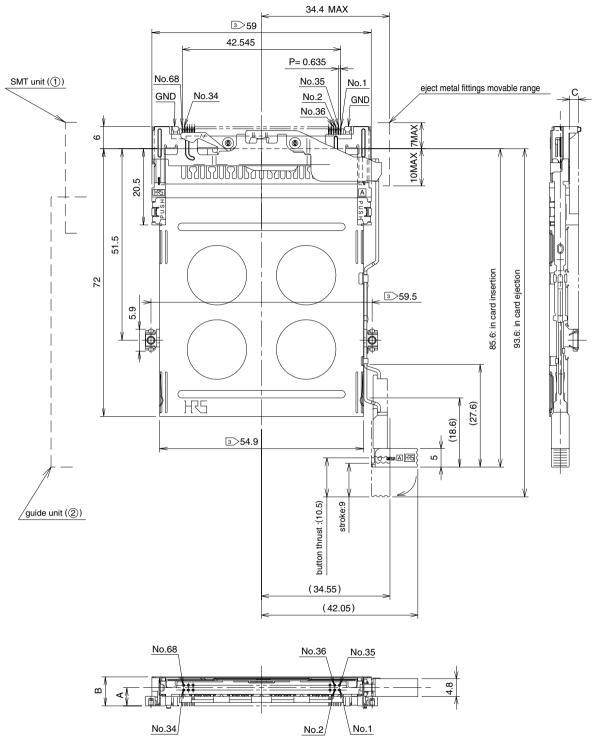


Standoff	①SMT unit ②Guide unit		①SMT unit		Α	В	С	Weight
type	Part Number	CL No.	Part Number	CL No.	(mm)	(mm)	(mm)	(g)
none	IC11S-68PLR-1.27SF-EJL	640-1004-5	IC11S-BUR-EJL	640-1056-9	2.7	5.6	0.1	13.1
2.2mm	IC11SA-68PLR-1.27SF-EJL	640-1006-0	IC11SA-BUR-EJL	640-1058-4	4.9	7.8	2.3	13.6

Note.1) This figure illustrates grouping of SMT unit(1) and guide unit(2) together.

Note.2) Dimensions for card fitting are in accordance with "PC Card Standard".

Right flexible button type

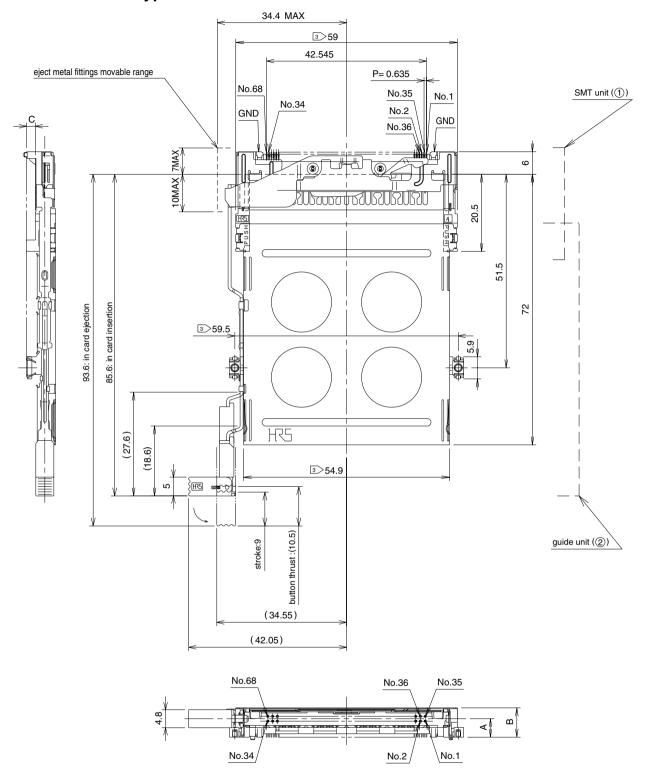


Standoff	Standoff ①SMT unit		②Guide ui	Α	В	С	Weight	
type	Part Number	CL No.	Part Number	CL No.	(mm)	(mm)	(mm)	(g)
none	IC11S-68PLR-1.27SF-EJR	640-1003-2	IC11S-BUR-FEJR	640-1059-7	2.7	5.6	0.1	13.5
2.2mm	IC11SA-68PLR-1.27SF-EJR	640-1005-8	IC11SA-BUR-FEJR	640-1061-9	4.9	7.8	2.3	14

Note.1) This figure illustrates grouping of SMT unit(1) and guide unit(2) together.

Note.2) Dimensions for card fitting are in accordance with "PC Card Standard".

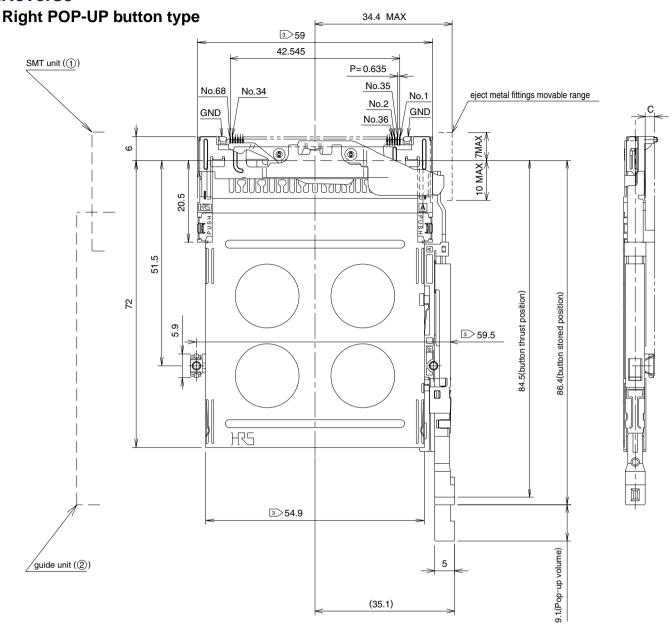
Left flexible button type

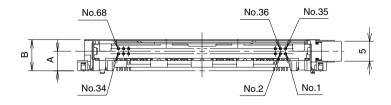


Stan	Standoff ①SMT unit		it	②Guide u	Α	В	С	Weight	
typ	ре	Part Number	CL No.	Part Number	CL No.	(mm)	(mm)	(mm)	(g)
no	ne	IC11S-68PLR-1.27SF-EJL	640-1004-5	IC11S-BUR-FEJL	640-1060-6	2.7	5.6	0.1	13.5
2.21	mm	IC11SA-68PLR-1.27SF-EJL	640-1006-0	IC11SA-BUR-FEJL	640-1062-1	4.9	7.8	2.3	14

Note.1) This figure illustrates grouping of SMT unit(1) and guide unit(2) together.

Note.2) Dimensions for card fitting are in accordance with "PC Card Standard".



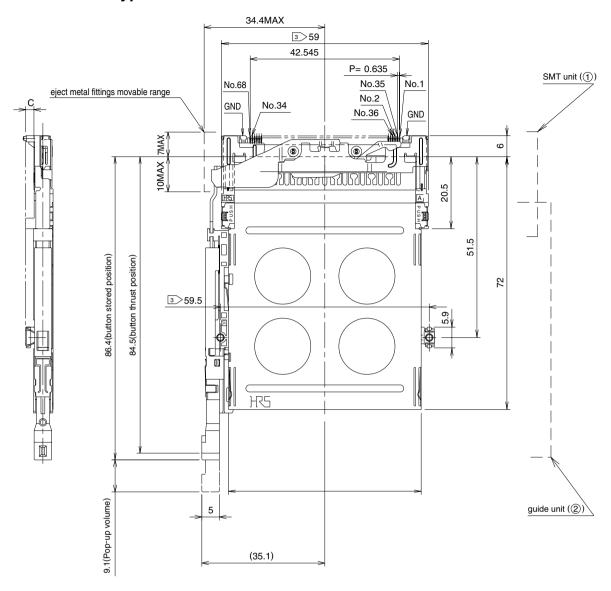


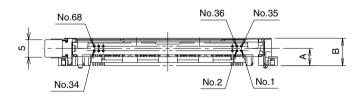
Standoff	①SMT un	it	②Guide unit		Α	В	С	Weight
type	Part Number	CL No.	Part Number	CL No.	(mm)	(mm)	(mm)	(g)
none	IC11S-68PLR-1.27SF-EJR	640-1003-2	IC11S-BUR-PEJR	640-1065-0	2.7	5.6	0.1	15.1
2.2mm	IC11SA-68PLR-1.27SF-EJR	640-1005-8	IC11SA-BUR-PEJR	640-1067-5	4.9	7.8	2.3	15.6

Note.1) This figure illustrates grouping of SMT unit(1) and guide unit(2) together.

Note.2) Dimensions for card fitting are in accordance with "PC Card Standard".

Left POP-UP button type





Standoff	①SMT unit ②Guide unit		①SMT unit		Α	В	С	Weight
type	Part Number	CL No.	Part Number	CL No.	(mm)	(mm)	(mm)	(g)
none	IC11S-68PLR-1.27SF-EJL	640-1004-5	IC11S-BUR-PEJL	640-1066-2	2.7	5.6	0.1	15.1
2.2mm	IC11SA-68PLR-1.27SF-EJL	640-1006-0	IC11SA-BUR-PEJL	640-1068-8	4.9	7.8	2.3	15.6

Note.1) This figure illustrates grouping of SMT unit(1) and guide unit(2) together.

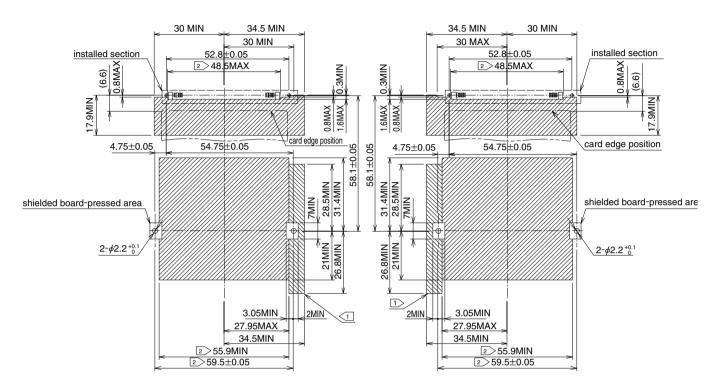
Note.2) Dimensions for card fitting are in accordance with "PC Card Standard".

■PCB mounting pattern

Standard Type

●Without standoff

(right button)

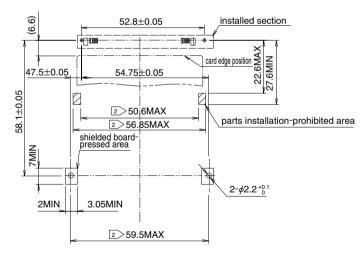


Without standoff

(left button)

●Standoff 2.2mm

(common to both right and left buttons)

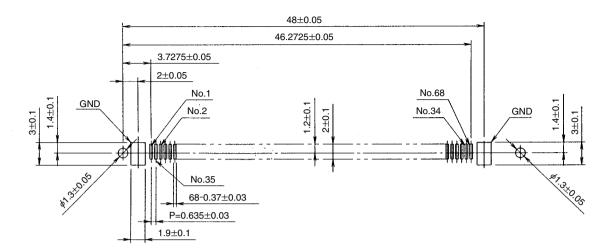


Note.1) area and area show the pattern-inhibited area.

However ∭ area will be the pattern-inhibited area only when guide unit is "IC11S-BD-PEJ*".

● PCB mounting pattern (Enlarged)

●Standard type



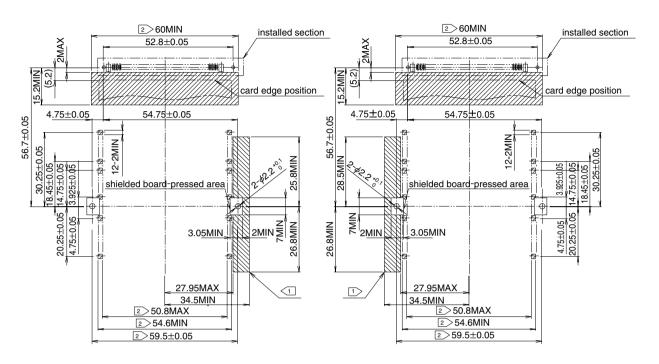
Reverse Type

●Without standoff

(right button)

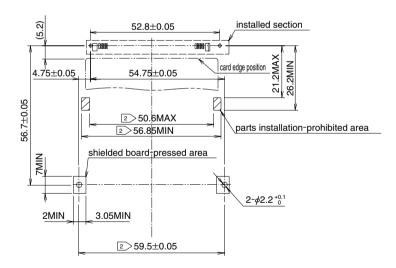
●Without standoff

(left button)



●Standoff 2.2mm

(common to both right and left buttons)

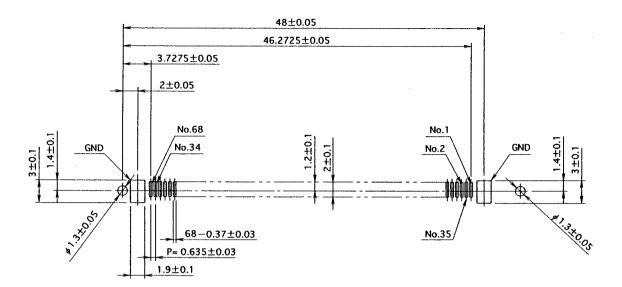


Note.1) area and area show the pattern-inhibited area.

However area will be the pattern-inhibited area only when guide unit is "IC11S-BUR-PEJ".

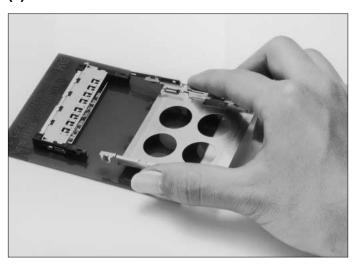
● PCB mounting pattern (Enlarged)

●Reverse type

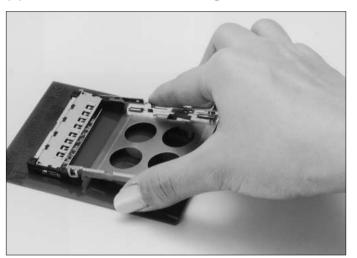


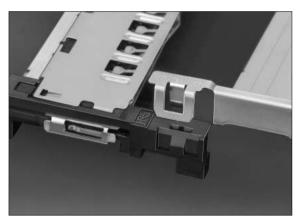
■How To Install In Board(Standard Type)

(1)Install SMT unit.

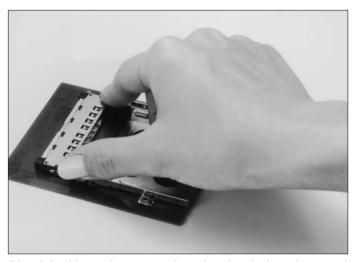


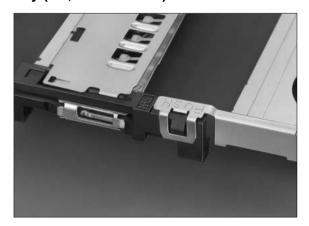
(2)Position the lock section of guide unit into the hole of SMT unit.





(3)Press the lock top of guide unit to push into SMT unit securely (i.e., until clicked.)





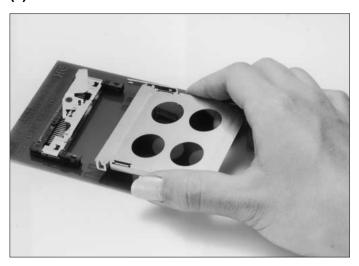
(Note.) Avoid pressing any section other than lock top because it may cause guide plate deformation.

(4)Screw 2 spots to guide unit from the back side of board.

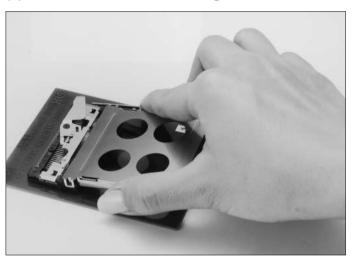
Screw designation	Pitch	Recommended tightening torque
M2	0.4	1.5 to 2.0 (kgf • cm)

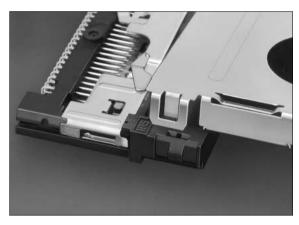
■How To Install In Board(Reverse Type)

(1)Install SMT unit.

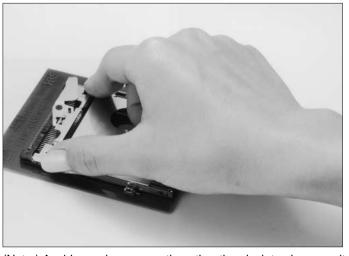


(2)Position the lock section of guide unit into the hole of SMT unit.





(3)Press the lock top of guide unit to push into SMT unit securely (i.e., until clicked.)





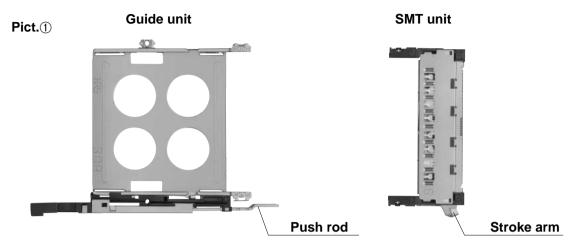
(Note.) Avoid pressing any section other than lock top because it may cause guide plate deformation.

(4)Screw 2 spots to guide unit from the back side of board.

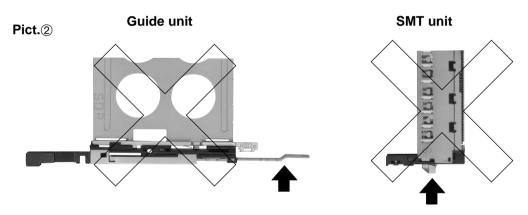
Screw designation	Pitch	Recommended tightening torque
M2	0.4	1.5 to 2.0 (kgf • cm)

■PreCautions In Installation To Boards

1. After installation of SMT unit to boards, verify that the stroke arm of SMT unit and the push rod of guide unit are located on the positions shown in fig.①. Also note that guide unit cannot be solder reflowed.



2. Note that the stroke arm of SMT unit and the push rod of guide unit cannot be combined when located in the position as shown in fig. ②.

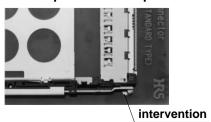


If located in the position shown in fig. 2 move it to the position shown in fig. 1 by fingers.

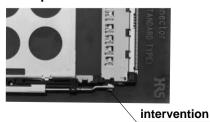


3. After SMT unit and guide unit are combined, state will be found as follows:



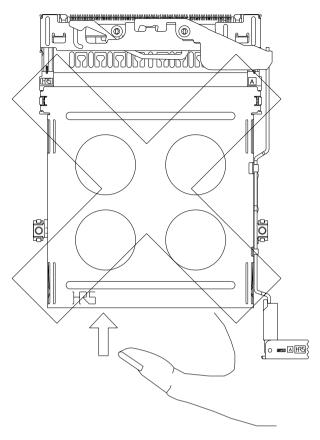




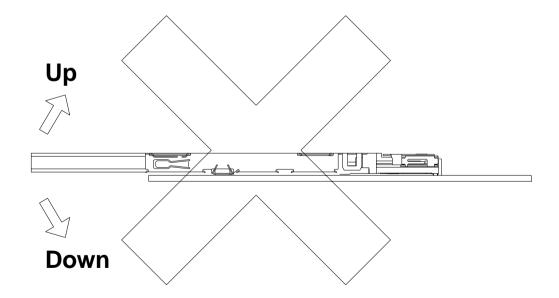


■Pre Caution In Handling

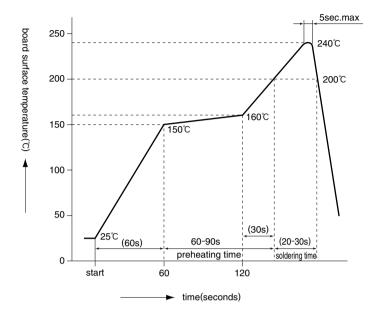
Guide plate is metallic, having some sharp-edged portions. Handle carefully to prevent injury to fingers.



Do not wrench the card up and down severely in the midst of insertion. This may cause damage to the connectors or cards.



■Temperature Profile



Applicable Conditions

Reflow system : IR reflow

Solder : Paste type 63 Sn/37 Pb

(Flux content 9 wt%)

Test board Glass epoxy 60mm x 60mm x 1.6 mm

Metal mask thickness: 0.15 mm

Recommended temperature profile.

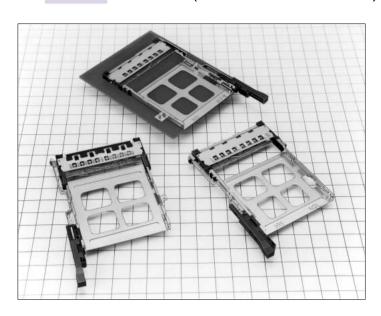
The temperature may be slightly changed according to the solder paste type and amount.

HS A25

Single Slot SMT Connectors For Card-Bus Based PC Cards

IC11S Series (New POP-UP Button)







■Features

1. PC Card Standard compliant:

- · Grounding is required to meet the high speed signal requirements of the PC card standard. Grounding reliability is achieved with a grounding plate and 8 grounding contacts.
- · Type I, type II and type III cards are covered.
- · Terminals for ground clipping are provided.

2. Reduced pattern-inhibited area

Pattern-inhibited area is reduced, compared to our conventional product.

3. Light-Weight

Approx. 12% of weight reduced.

Compared to conventional type, it only weighs 13.1g for standard type with 0mm standoff.

4. Reduced Height:

Connector height is minimized to 5.6mm, making possible thinner product designs.

5. Eject mechanism with high-level functionality

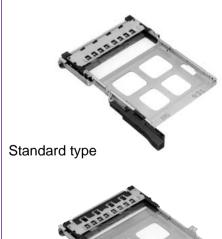
Hirose Electric's original ejection mechanism provides an higher degree of card ejection over existing products. This improves the operational qualities of card removal. (Patents pending)

6. Wide Variety of Options Available

- · Standard type mounts to the top of the PC board and reverse type mounts on the underside of the board
- · Three types of eject buttons; rigid, flexible and POP-UP.All types can be installed on the right or left side of the ejector.
- · Available with standoff to utilize space under the connector for mounting other parts.

Wide variety of options

- (1)Board Mounting
 - ①Standard type
 - ②Reverse type
- (2)Position of eject buttons
 - **1**Right
 - ²Left
- (3)Standoffs
 - ① 0mm
 - 22.2mm





■Product Specifications

	Current rating	0.5A	Operating temperature	-55℃ to +85℃(Note.1)	Storage temperature	-40°C to +70°C(Note.2)
Ratings	Voltage rating	125V AC	Operating humidity	Relativehumidity 95% or less (With no dew-fall)	Storage humidity	40% to 70%(Note.2)

Item	Specification	Conditions
1.Insulation resistance	1000M ohms min.	500V DC
2.Withstanding voltage	No flashover or insulation breakdown.	500V AC
3.Contact resistance	60m ohms max. (initial value)	1mA
4.Vibration	No electrical discontinuity of 100ns or more	Frequency: 10 to 2000 Hz, full amplitude of 1.52 mm or acceleration of 147 m/s²(peak), 4 hours in each of the 3 directions.
5.Humidity (Steady state)	Insulation resistance: 100M ohms min.	96 hours at temperature of 40°C and humidity of 90% to 95%
6.Temperature cycle	Insulation resistance: 100M ohms min.	(-55°C:30min.→+5°C to 35°C:MAX 5min→85°C:30min→ +5-35°C:MAX 5min.) 5 cycles
7.Durability (Insertion/withdrawal)	Variations from initial contact resistance: 20m ohms max.	10000 cycles at 400 to 600 cycles per hour
8.Resistance to	No deformation of components affecting performance.	Reflow: At the recommended temperature profile
Soldering heat	no deformation of components affecting performance.	Manual soldering: 300℃ for 3 seconds

Note 1: Includes temperature rise caused by current flow.

Note 2: The term "storage" refers to products stored for long period of time prior to mounting and use. Operating Temperature Range and Humidity range covers non- conducting condition of installed connectors in storage, shipment or during transportation.

■Materials

●SMT unit

	Parts	Material	Finish	Remarks
Insulator		PPS	Color : Black	UL94V-0
Terminal	Card connected section	Brass	Contact section: gold plating Lead section: solder plating	
reminal	Ground plate	Phosphor bronze	Contact section: gold plating Lead section: solder plating	
Eject metal fittings		Stainless steel		

●Guide unit

Desc	ription	Material	Finish	Remarks
Guide plate		Stainless steel		
Push rod		Stainless steel		
	Resin section	PBT	Color : Black	UL94V-0
Eject Button	Spring	Steel		
	Cam	Zinc alloy		

■Ordering Information

SMT Unit

$$\frac{\text{IC11S}}{\bullet} \ \frac{A}{@} - \frac{68}{\bullet} \ \frac{\text{PLR}}{\bullet} - \frac{1.27\text{SF}}{\bullet} - \frac{\text{EJ}}{\bullet} \ \frac{\text{R}}{\bullet}$$

Series name : IC11S	6 1.27SF : 1.27mm pitch SMT connector
Standoff type	
Blank : none	With ejector
A : 2.2mm	
3 Number of contacts : 68	
4 Board Mounting Method:	Eject button positions
PL : standard type	R : right
PLR : reverse type	L : left

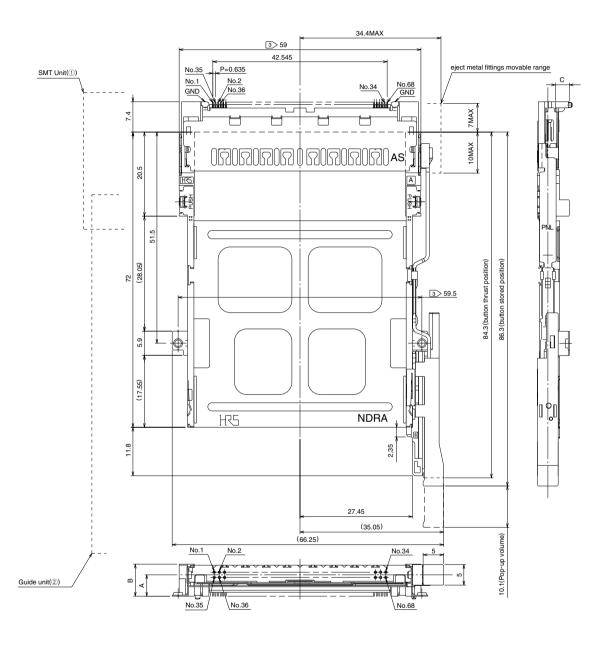
●Guide Unit

8	Series name : IC11S	0	Eject button type
9	Standoff type		PNEJ: POP-UP button
	Blank: none		
	A: 2.2mm		
1	Board Mounting Method	12	Eject button positions
	BD : standard type		R : right
	BUR : reverse type		L : left

(Note.) IC11S Series will be used in combination of SMT unit with guide unit. When using, please select the same type for the following items. Note that other combinations cannot be used.

> • Series name (⊕⇔8) • Standoff type (**②**⇔**③**) • Board Mounting Method (♠⇔♠) • Eject button positions **(7**⇔**12**)

Right POP-UP button type

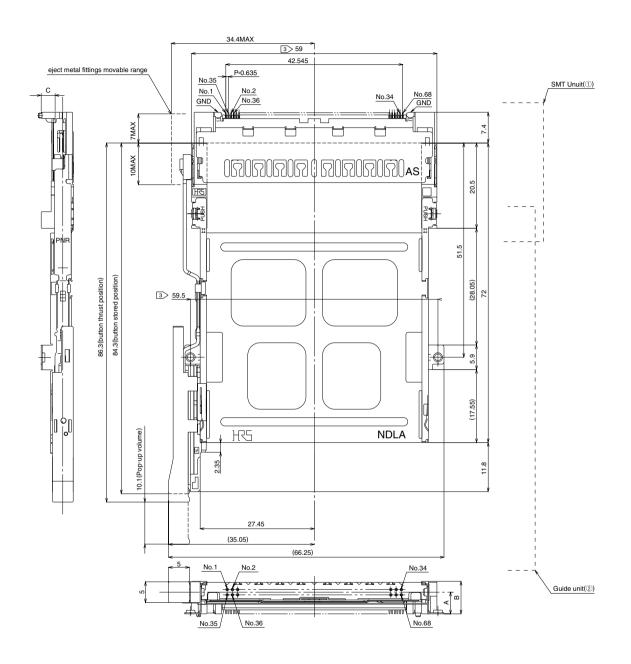


Standoff	①SMT unit		②Guide unit		Α	В	С	mass
type	Part Number	CL No.	Part Number	CL No.	(mm)	(mm)	(mm)	(g)
0mm	IC11S-68PL-1.27SF-EJR	640-1007-3	IC11S-BD-PNEJR	640-1251-4	3	5.6	0.1	13.1
2.2mm	IC11SA-68PL-1.27SF-EJR	640-1009-9	IC11SA-BD-PNEJR	640-1253-0	5.2	7.8	2.3	13.6

Note.1) This figure illustrates grouping of SMT unit(1) and guide unit(2) together.

Note.2) Dimensions for card fitting are in accordance with "PC Card Standard".

Left POP-UP button type

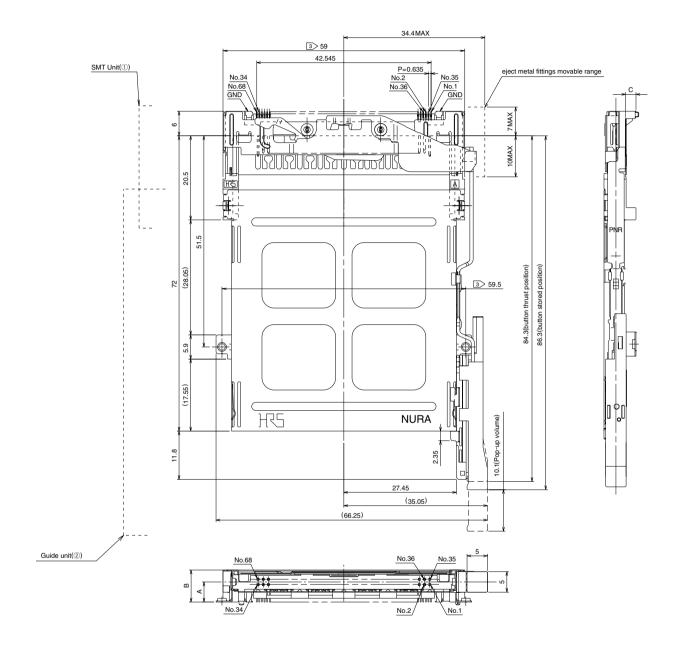


Standoff	①SMT unit		②Guide unit		Α	В	С	mass
type	Part Number	CL No.	Part Number	CL No.	(mm)	(mm)	(mm)	(g)
0mm	IC11S-68PL-1.27SF-EJL	640-1008-6	IC11S-BD-PNEJL	640-1252-7	3	5.6	0.1	13.1
2.2mm	IC11SA-68PL-1.27SF-EJL	640-1010-8	IC11SA-BD-PNEJL	640-1254-2	5.2	7.8	2.3	13.6

Note.1) This figure illustrates grouping of SMT unit(1) and guide unit(2) together.

Note.2) Dimensions for card fitting are in accordance with "PC Card Standard".

Right POP-UP button type

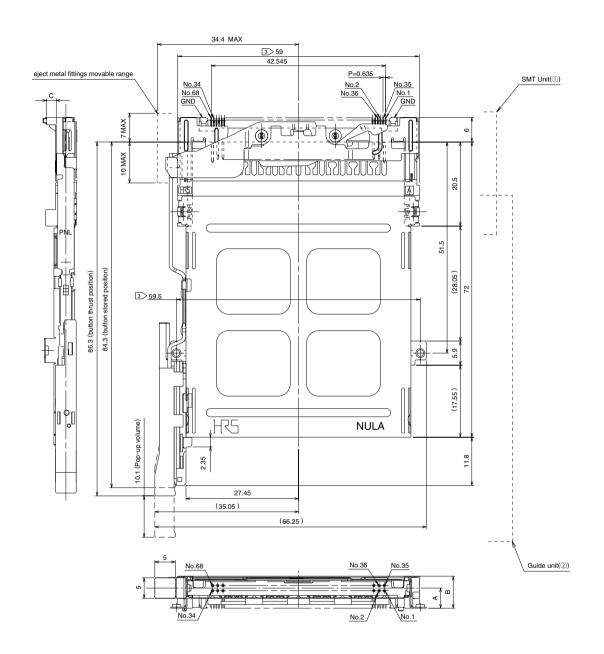


Standoff	①SMT unit		②Guide unit		Α	В	С	mass
type	Part Number	CL No.	Part Number	CL No.	(mm)	(mm) ((mm)	(g)
0mm	IC11S-68PLR-1.27SF-EJR	640-1003-2	IC11S-BUR-PNEJR	640-1255-5	2.7	5.6	0.1	13.3
2.2mm	IC11SA-68PLR-1.27SF-EJR	640-1005-8	IC11SA-BUR-PNEJR	640-1257-0	4.9	7.8	2.3	13.7

Note.1) This figure illustrates grouping of SMT unit(1) and guide unit(2) together.

Note.2) Dimensions for card fitting are in accordance with "PC Card Standard".

Left POP-UP button type



Standoff	①SMT unit		②Guide unit		Α	В	С	mass
type	Part Number	CL No.	Part Number	CL No.	(mm)	(mm)	(mm)	(g)
0mm	IC11S-68PLR-1.27SF-EJL	640-1004-5	IC11S-BUR-PNEJL	640-1256-8	2.7	5.6	0.1	13.3
2.2mm	IC11SA-68PLR-1.27SF-EJL	640-1006-0	IC11SA-BUR-PNEJL	640-1258-3	4.9	7.8	2.3	13.7

Note.1) This figure illustrates grouping of SMT unit(1) and guide unit(2) together.

Note.2) Dimensions for card fitting are in accordance with "PC Card Standard".

● PCB mounting pattern

Standard Type

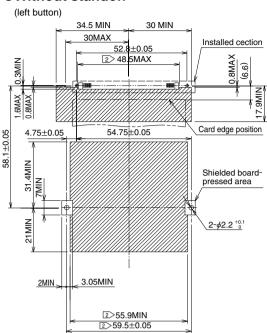
Without standoff

(right button) 30 MIN 34.5 MIN 30MAX Installed cection 52.8±0.05 2>48.5MAX (6.6) .8MAX 17.9MIN 0.8MAX Card edge position 4.75±0.05 54.75±0.05 58.1 31.4MIN Shielded board-pressed area 21MIN <u>2-φ2</u>.2 ⁺⁰.0 3.05MIN 2MIN

2>55.9MIN

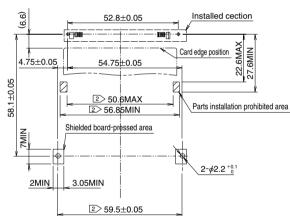
2>59.5±0.05

Without standoff



●Standoff 2.2mm

(common to both right and left buttons)

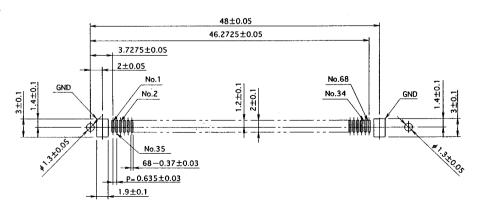


Note.1) area show the pattern-inhibited area.

Note.2) Indicated dimensions are symmetrical to the center of the card insertion slot.

● PCB mounting pattern (Enlarged)

Standard type

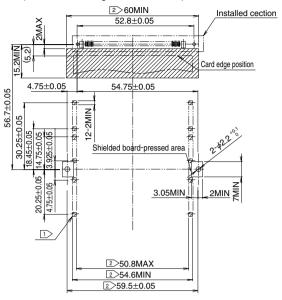


●PCB mounting pattern

Reverse Type

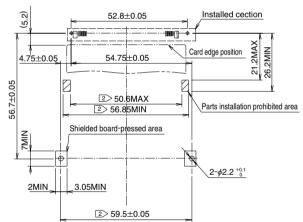
Without standoff

(common to both right and left buttons)



●Standoff 2.2mm

(common to both right and left buttons)

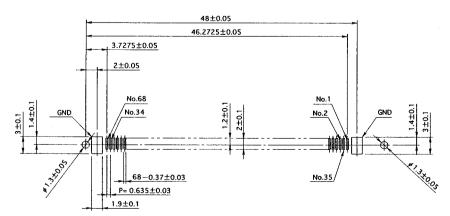


Note.1) area show the pattern-inhibited area.

Note.2) Indicated dimensions are symmetrical to the center of the card insertion slot.

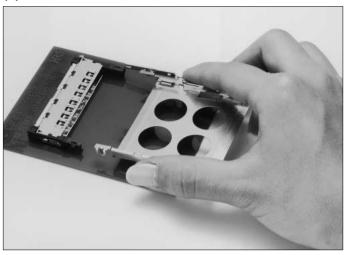
▶PCB mounting pattern (Enlarged)

Reverse type

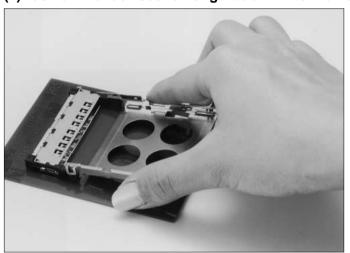


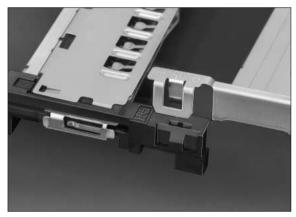
● How To Install In Board(Standard Type)

(1)Install SMT unit.

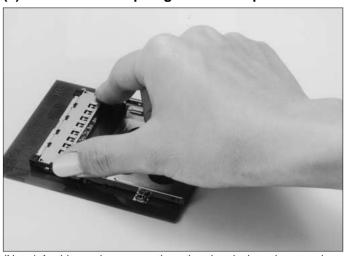


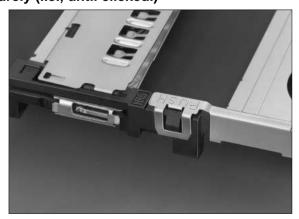
(2)Position the lock section of guide unit into the hole of SMT unit.





(3)Press the lock top of guide unit to push into SMT unit securely (i.e., until clicked.)





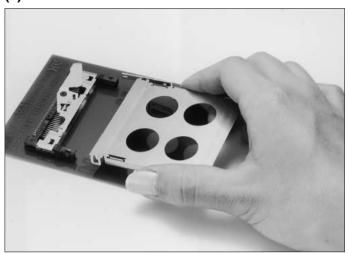
(Note.) Avoid pressing any section other than lock top because it may cause guide plate deformation.

(4)Screw 2 spots to guide unit from the back side of board.

Screw designation	Pitch	Recommended tightening torque
M2	0.4	0.14 to 0.18 (N • m)

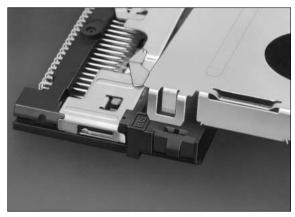
●How To Install In Board(Reverse Type)

(1)Install SMT unit.

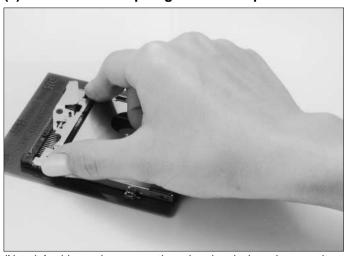


(2)Position the lock section of guide unit into the hole of SMT unit.





(3)Press the lock top of guide unit to push into SMT unit securely (i.e., until clicked.)





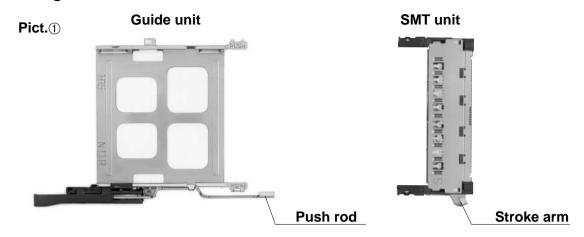
(Note.) Avoid pressing any section other than lock top because it may cause guide plate deformation.

(4)Screw 2 spots to guide unit from the back side of board.

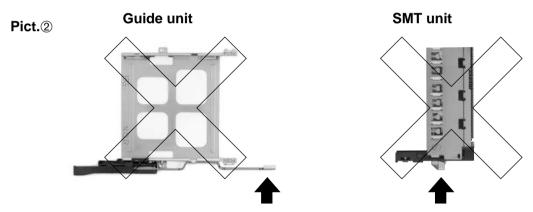
Screw desi	gnation	Pitch	Recommended tightening torque
M2		0.4	0.14 to 0.18 (N • m)

Cautions In Installation To Boards

1. After installation of SMT unit to boards, verify that the stroke arm of SMT unit and the push rod of guide unit are located on the positions shown in fig.①. Also note that guide unit cannot be solder reflowed.



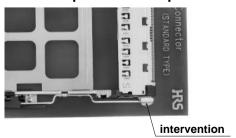
2. Note that the stroke arm of SMT unit and the push rod of guide unit cannot be combined when located in the position as shown in fig. 2.



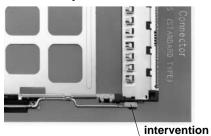
If located in the position shown in fig. ② move it to the position shown in fig. ① by fingers.



- 3. After SMT unit and guide unit are combined, state will be found as follows:
 - •When the push rod was pressed:

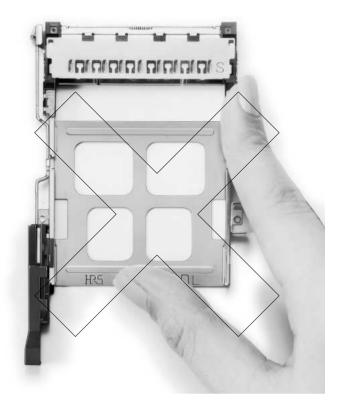


●When the push rod was extracted:

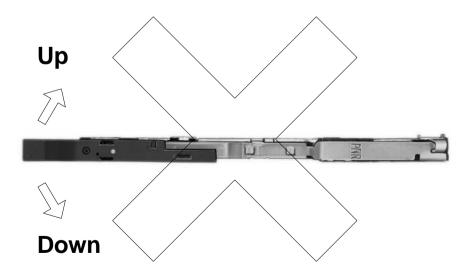


◆Caution In Handling

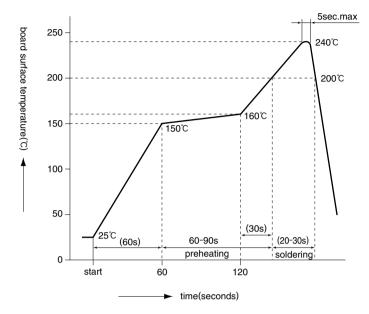
Guide plate is metallic, having some sharp-edged portions. Handle carefully to prevent injury to fingers.



Do not wrench the card up and down severely in the midst of insertion. This may cause damage to the connectors or cards.



●Installation Temperature Profile



Applicable Conditions

Reflow system : IR reflow

Solder : Paste type 63 Sn/37 Pb

(Flux content 9 wt%)

Test board Glass epoxy 60mm x 60mm x 1.6 mm

Metal mask thickness: 0.15 mm

Recommended temperature profile.

The temperature may be slightly changed according to the

solder paste type and amount.